

NEO-RD Series

Advanced Wafer Rinse & Dry

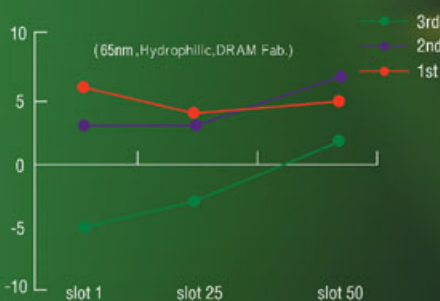
Key Features

- Nano Technology
- One Way Stream
- Le Chatelier's Principle
- Watermark Free
- Dome shape multi-tasking chamber
- Room temp. process

Applicable Process

- Silicon wafer process (4"~12")
- Thin wafer process ($\geq 70\mu\text{m}$)
- HDD process (0.89"~3.5")
- Photo-mask process
(150 X 150~800 X 960)

Particle performance



As seen on graph, NEO-series proven to yield excellent result in 65nm particle through ample supply of IPA and application of a new system concept

